Electronic Pate	nt App	lication Fee	Transm	ittal			
Application Number:	105	10598142					
Filing Date:	18-	18-Aug-2006					
Title of Invention:		HEATER, REFLOW APPARATUS, AND SOLDER BUMP FORMING METHOD ANN APPARATUS					
First Named Inventor/Applicant Name:	Ma	Masaru Shirai					
Filer:	End	Enoch E. Peavey/Elizabeth Whiting					
Attorney Docket Number:	P30	P30470					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Fi	ling Fee	;					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Utility Appl issue fee		1501	1	1510	1510		

Publ. Fee- early, voluntary, or normal

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
	Total in USD (\$)			1810